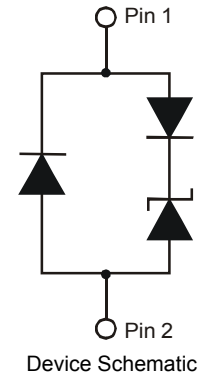
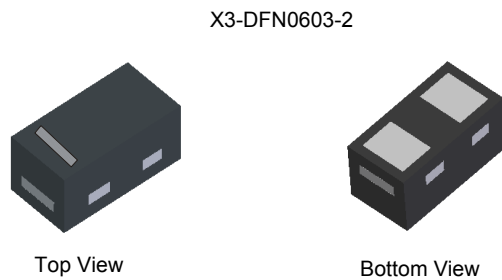


Features

- Ultra-Small, Low Profile Leadless Surface Mount Package (0.6 * 0.3 * 0.3mm)
- IEC 61000-4-2 (ESD): Air – ±20kV, Contact – ±15kV
- 1 Channel of ESD Protection
- Low Channel Input Capacitance of 0.5pF Typical
- Typically Used at High Speed Ports such as USB 3.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: X3-DFN0603-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin over Copper leadframe, solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.0002 grams (approximate)



Ordering Information (Note 4)

Product	Compliance	Marking	Reel size(inches)	Tape width(mm)	Quantity per reel
D5V0F1U2LP3-7	Standard	TK	7	8	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>

Marking Information



TK = Product Type Marking Code
Bar Denotes Pin 1 or Cathode Side

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I_{PP}	1.5	A	8/20 μs , Per Figure 3
ESD Protection – Contact Discharge	$V_{ESD \text{ Contact}}$	± 15	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	$V_{ESD \text{ Air}}$	± 20	kV	Standard IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	—	—	5.5	V	—
Reverse Current (Note 6)	I_R	—	—	100	nA	$V_R = 5.0\text{V}$
Reverse Breakdown Voltage	V_{BR}	6.0	—	—	V	$I_R = 1\text{mA}$
Reverse Clamping Voltage, Positive Transients (Note 7)	V_{CL}	—	10	12	V	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$
Dynamic Resistance	R_{DYN}	—	0.9	—	Ω	$I_R = 1\text{A}, t_p = 8/20\mu\text{s}$
Capacitance (Note 8)	C_T	—	0.4	0.65	pF	$V_R = 2.5\text{V}, f = 1\text{MHz}$
		—	0.5	—	pF	$V_R = 0\text{V}, f = 1\text{MHz}$

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.
 - Clamping voltage value is based on an 8x20 μs peak pulse current (I_{PP}) waveform.
 - Measured from any I/O to GND.
 - For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: http://www.diodes.com/destdtools/appnote_dnote.html.

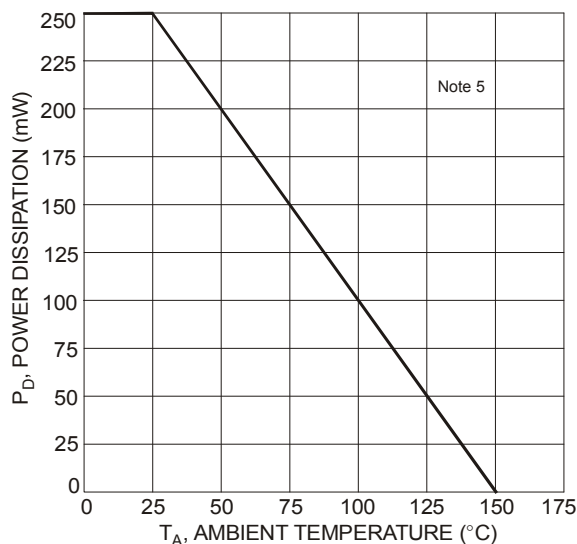


Figure 1 Power Derating Curve

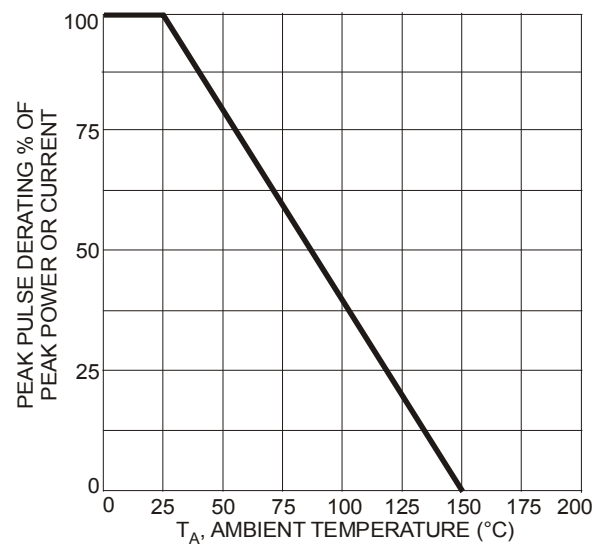


Figure 2 Pulse Derating Curve

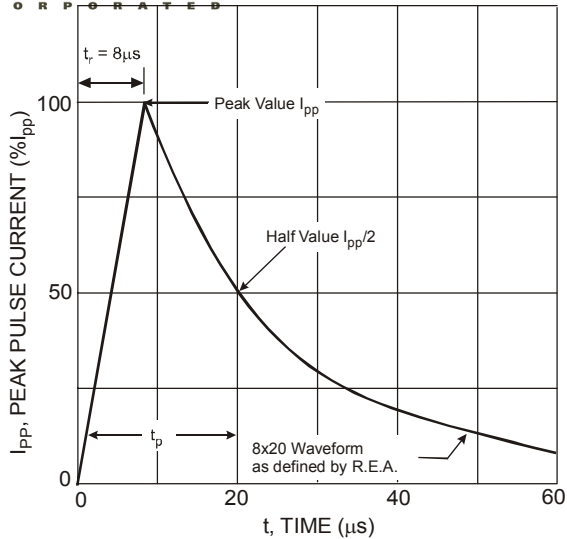


Figure 3 Pulse Waveform

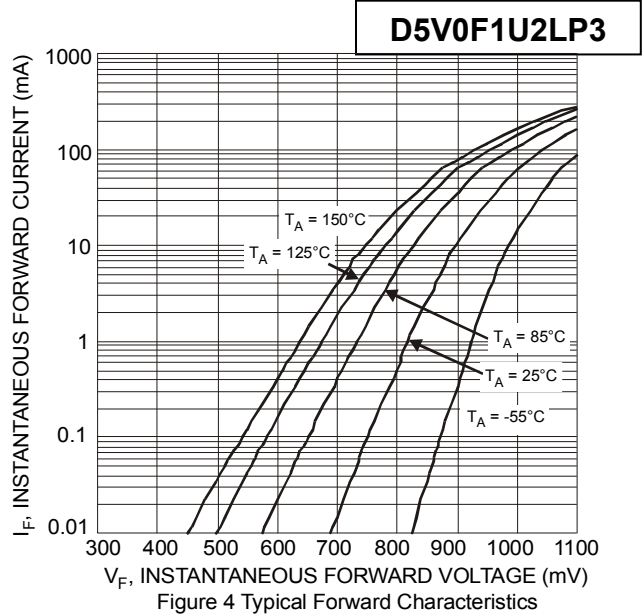


Figure 4 Typical Forward Characteristics

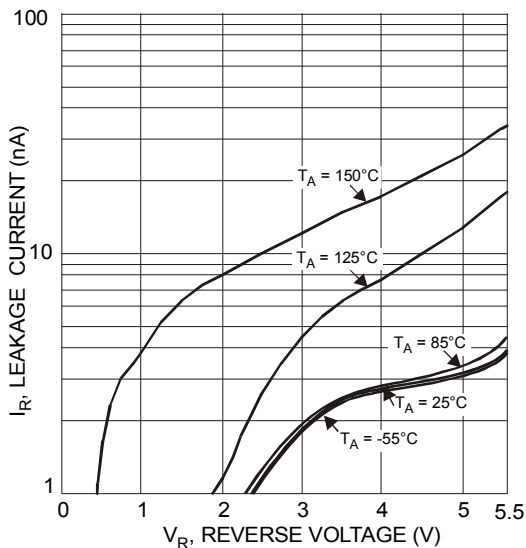


Figure 5 Typical Reverse Characteristics

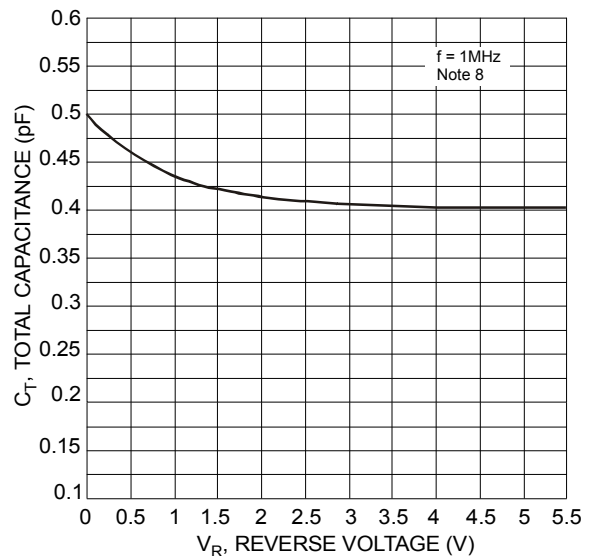
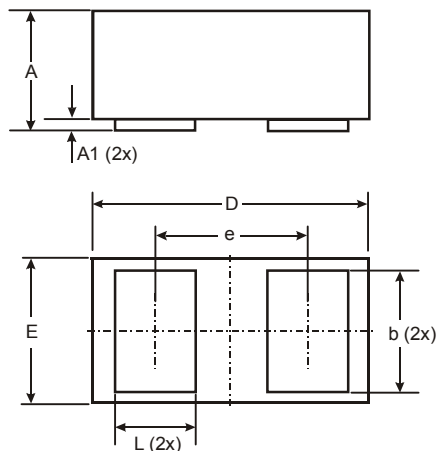


Figure 6 Total Capacitance vs. Reverse Voltage

Package Outline Dimensions

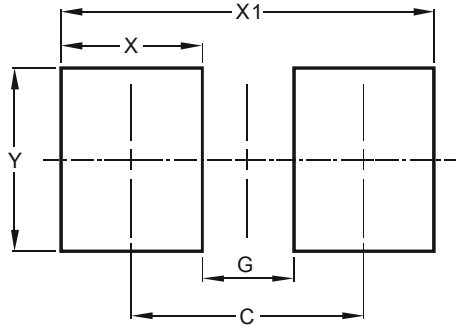
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X3-DFN0603-2			
Dim	Min	Max	Typ
A	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
E	0.295	0.345	0.32
e	-	-	0.355
L	0.14	0.24	0.19
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.355
G	0.150
X	0.230
X1	0.610
Y	0.300

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